



Cite this: *Nanoscale*, 2014, 6, 14453

## Novel chemical route for atomic layer deposition of MoS<sub>2</sub> thin film on SiO<sub>2</sub>/Si substrate†

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Recently MoS<sub>2</sub> with a two-dimensional layered structure has attracted great attention as an emerging material for electronics and catalysis applications. Although atomic layer deposition (ALD) is well-known as a special modification of chemical vapor deposition in order to grow a thin film in a manner of layer-by-layer, there is little literature on ALD of MoS<sub>2</sub> due to a lack of suitable chemistry. Here we report MoS<sub>2</sub> growth by ALD using molybdenum hexacarbonyl and dimethyldisulfide as Mo and S precursors, respectively. MoS<sub>2</sub> can be directly grown on a SiO<sub>2</sub>/Si substrate at 100 °C via the novel chemical route. Although the as-grown films are shown to be amorphous in X-ray diffraction analysis, they clearly show characteristic Raman modes (E<sub>2g</sub><sup>1</sup> and A<sub>1g</sub>) of 2H-MoS<sub>2</sub> with a trigonal prismatic arrangement of S–Mo–S units. After annealing at 900 °C for 5 min under Ar atmosphere, the film is crystallized for MoS<sub>2</sub> layers to be aligned with its basal plane parallel to the substrate.

Received 20th August 2014,  
Accepted 13th October 2014

DOI: 10.1039/c4nr04816d

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## 1 Introduction

Due to the success in recent research on graphene and its various applications,<sup>1</sup> two-dimensional (2D) materials such as transition metal dichalcogenides (TMDs) have attracted great attention in academia and industry.<sup>2,3</sup> Among the TMDs (MX<sub>2</sub>), where M is a transition metal of groups 4–10 and X is a chalcogen, MoS<sub>2</sub> is one of the potential materials for electronics and catalysis applications.<sup>4,5</sup> While bulk MoS<sub>2</sub> is an n-type semiconductor with an indirect bandgap (~1.3 eV), the atomic monolayer of MoS<sub>2</sub> has a direct bandgap (~1.8 eV).<sup>6</sup> Several groups have reported performance of MoS<sub>2</sub> in field effect transistors and logic devices in which a monolayer or a film of MoS<sub>2</sub> was used as a semiconducting channel in the transistor, instead of silicon.<sup>7–9</sup> In addition, MoS<sub>2</sub> is a strong candidate to replace expensive Pt catalyst in the electrochemical hydrogen evolution reaction (HER) for renewable H<sub>2</sub> production.<sup>10,11</sup>

For the electronic device applications of 2D materials, they should have a bandgap to ensure a high on/off ratio of the transistor, and should be directly grown with a high crystallinity on an insulating material (e.g., SiO<sub>2</sub>). However, since graphene has intrinsically no bandgap and cannot be grown without a catalytic film (e.g., Ni and Cu), the performance of the graphene transistor is not as excellent as expected from theoretical calculations and the best experimental mobility

(10<sup>5</sup> cm<sup>2</sup> V<sup>-1</sup> s<sup>-1</sup>) was obtained by using an exfoliated graphene.<sup>12</sup> It was recently reported that a monolayer or ultrathin film of MoS<sub>2</sub> could be directly grown on an insulator without any catalyst by chemical vapor deposition (CVD).<sup>13–16</sup> However, a common problem of CVD methods is that elemental sulfur is used as a sulfur precursor for MoS<sub>2</sub> CVD. The vapor pressure of elemental sulfur is ~10<sup>-5</sup> Torr at 40 °C, which is much lower in comparison to typical vapor pressures of CVD precursors.<sup>17</sup> Even though large-area MoS<sub>2</sub> monolayers were demonstrated by the CVD method, it cannot be utilized in mass production due to a lack of reliability and reproducibility of the process.

On the other hand, atomic layer deposition (ALD) is a special modification of CVD for growing a thin film via a self-limiting mechanism.<sup>18</sup> In CVD, while two precursors (e.g., Mo and S precursors) are simultaneously supplied to a substrate, they are alternately exposed onto the substrate and subsequently purged for each precursor in ALD. Therefore one ALD cycle generally consists of two half reactions, which are achieved by repeating four steps (the first precursor exposure and purging steps for the first half reaction and the second precursor exposure and purging steps for the second half reaction). In addition, growth temperature in ALD is maintained to be low enough in order to avoid thermal decomposition of the precursors. Consequently, the film grows with the number of ALD cycles via chemisorption of each precursor, which occurs in turn repeatedly. Considering the principle of ALD being based on chemisorption, it is expected that ALD may be an excellent tool for preparing layered MoS<sub>2</sub>.

Recently, a MoO<sub>3</sub> thin film was grown by ALD using molybdenum hexacarbonyl (Mo(CO)<sub>6</sub>) and various oxidants.<sup>19</sup> ALD of

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† Electronic supplementary information (ESI) available: XPS depth profiles for the as-grown and the annealed MoS<sub>2</sub> films. See DOI: 10.1039/c4nr04816d

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a Mo thin film was also reported by using MoF<sub>6</sub> and Si<sub>2</sub>H<sub>6</sub>.<sup>20</sup> A MoS<sub>2</sub> HER catalyst was prepared by sulfurizing a MoO<sub>3</sub> thin film, which was grown by ALD from Mo(CO)<sub>6</sub> and ozone.<sup>21</sup> Very recently, the first report on ALD of MoS<sub>2</sub> was presented by Loh *et al.* by using MoCl<sub>5</sub> and H<sub>2</sub>S on sapphire substrates.<sup>22</sup> To the best of our knowledge, this is the only paper for MoS<sub>2</sub> ALD ever reported, due to a lack of suitable chemistry for ALD. Here we present a novel chemical route for MoS<sub>2</sub> ALD in which MoS<sub>2</sub> can be directly grown on a SiO<sub>2</sub>/Si substrate using Mo(CO)<sub>6</sub> and dimethyldisulfide (CH<sub>3</sub>SSCH<sub>3</sub>, DMDS) as Mo and S precursors, respectively.

## 2 Experimental

In order to investigate the growth behavior of MoS<sub>2</sub> using the novel chemistry of ALD, thin films were simultaneously grown on both SiO<sub>2</sub> (300 nm)/Si (1 × 1 or 2 × 2 cm<sup>2</sup>) and bare Si wafers in a laminar flow type ALD reactor. The films grown on the bare Si were used to measure the thickness by spectroscopic ellipsometry (SE). Mo(CO)<sub>6</sub> and DMDS (Aldrich) were vaporized from external canisters at room temperature and led into the reactor through solenoid valves with a carrier gas of N<sub>2</sub> (100 sccm, 99.999%) for Mo(CO)<sub>6</sub> and without any carrier gas for DMDS. The doses of Mo(CO)<sub>6</sub> and DMDS were ~1.8 × 10<sup>-6</sup> and ~4.0 × 10<sup>-4</sup> mol s<sup>-1</sup>, respectively. For purging the reactor, N<sub>2</sub> gas was used with a flow rate of 300 sccm. All delivery lines were maintained at 80 °C. The growth temperature was controlled by using a lamp heater, and monitored with a thermocouple which was closely placed to the specimen. The base pressure of the reactor was less than 10 mTorr and ALD was processed at a working pressure range of 1.4–3.3 Torr.

All thicknesses of the grown films were measured by SE (MG-1000, NanoView). The incident angle of the polarized light in the SE was fixed at around 70°, and the incident light has a spectral range of 1.5–5.0 eV. The measured data by SE was fitted with a Tauc–Lorentz dispersion function in order to determine the thickness.<sup>23</sup> Raman spectroscopy (Alpha 500R, WiTec) was used to characterize MoS<sub>2</sub> films using a 532 nm laser excitation. The Si peak at 521 cm<sup>-1</sup> was used as a reference for wavenumber calibration. X-ray photoelectron spectroscopic (XPS) spectra were obtained on a PHI 5000 Versaprobe (ULVAC PHI) using monochromatic Al Kα emission. Binding energies were measured using the C 1s peak (284.8 eV) of the adventitious carbon as an internal standard. X-ray diffraction (XRD) measurements were carried out in  $\theta/2\theta$  scan mode using a Philips X'pert Pro MRD X-ray diffractometer with Cu Kα emission. The high resolution transmission electron microscopy (HR-TEM) sample was prepared by using a focused ion beam and its microstructure was imaged in a TITAN TM 80-300 FEI microscope.

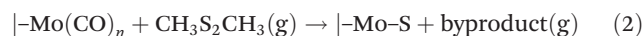
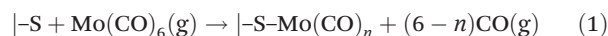
## 3 Results and discussion

### 3.1 Self-limiting growth of MoS<sub>2</sub> thin film by ALD

Although Mo(CO)<sub>6</sub> is a solid at ambient condition, it has a vapor pressure of 0.10–0.15 Torr at room temperature, which is

enough for deposition process in vacuum.<sup>24,25</sup> Several groups have used Mo(CO)<sub>6</sub> as a Mo precursor in ALD or CVD of MoO<sub>3</sub> thin films.<sup>19,26,27</sup> It is well known that physisorbed Mo(CO)<sub>6</sub> undergoes decarbonylation to form chemisorbed subcarbonyls, Mo(CO)<sub>*n*</sub> (*n* ≤ 5), on the surface of various substrates.<sup>28–31</sup> Therefore Mo(CO)<sub>6</sub> was chosen as a Mo precursor for the first-half reaction of ALD.

Chemisorption of organosulfur compounds (*e.g.*, DMDS) has been intensively studied due to their importance in hydrodesulfurization catalysis, self-assembled monolayers and so on.<sup>32,33</sup> There are several reports for dissociative chemisorption of DMDS through S–S bond cleavage to form methylthiolate intermediate (CH<sub>3</sub>S<sup>-</sup>) on the surface of various substrates.<sup>32–36</sup> The surface methylthiolates can undergo additional decomposition *via* C–S bond cleavage to produce sulfur adatoms releasing gaseous molecules such as (CH<sub>3</sub>)<sub>2</sub>S and CH<sub>3</sub>CH<sub>3</sub>. This reaction is utilized in thiol desulfurization by using Mo, sulfided Mo, or Mo(CO)<sub>6</sub> catalysts.<sup>33</sup> Because it is expected that the formation of surface S atoms from the methylthiolates may be also catalyzed by the chemisorbed Mo(CO)<sub>*n*</sub>, DMDS was selected as a S precursor for the second-half reaction of ALD. As a result, the chemistry for our MoS<sub>2</sub> ALD may consist of the first- and second-half reactions given in eqn (1) and (2):



where |- denotes surface.

In order to confirm the self-limiting chemisorption of the precursors in each half-reaction, thicknesses of the films grown at 100 °C for 100 cycles were plotted against exposure times of Mo(CO)<sub>6</sub> and DMDS, shown in Fig. 1. The chemisorption of Mo(CO)<sub>6</sub> in the first-half reaction (Fig. 1a) shows the typical self-limiting growth at exposure times (*x*) of Mo(CO)<sub>6</sub> longer than 3 s due to the saturation of adsorption sites occupied by Mo(CO)<sub>*n*</sub>. Similarly, DMDS also follows the self-limiting growth mechanism as shown in Fig. 1b, however the thickness saturates in a much shorter exposure time (*y*) owing

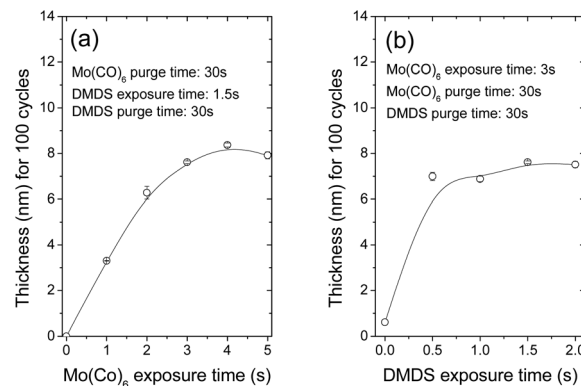


Fig. 1 Thicknesses of MoS<sub>2</sub> films against exposure times of Mo(CO)<sub>6</sub> (a) and DMDS (b). ALD was performed at 100 °C for 100 cycles. The curves are drawn for guiding the eye.

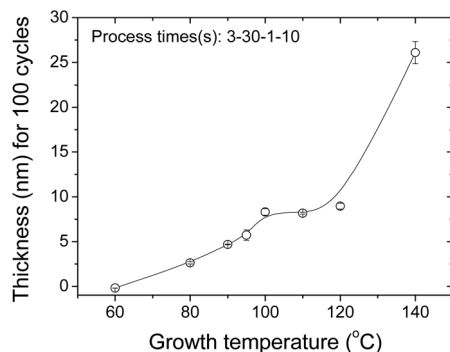


Fig. 2 Thickness of MoS<sub>2</sub> films against growth temperature. ALD was performed for 100 cycles with the process times given in the figure. The curves are drawn for guiding the eye.

to its high vapor pressure ( $\sim 29$  Torr at room temperature).<sup>37</sup> In addition, when one of both half-reactions was performed with only one precursor by making the exposure time of the other precursor be zero, the thickness increase by a deposit was negligible as shown with the thicknesses at  $x = 0$  (Fig. 1a) or  $y = 0$  (Fig. 1b). Consequently, we can exclude the possibility of uncontrolled thermal decomposition of both precursors in the film growth. It should be noted that when only DMDS was exposed without the exposure of Mo(CO)<sub>6</sub> (*i.e.*,  $x = 0$ ), the thickness of the deposit was also zero. However when the DMDS was exposed on the surface Mo(CO)<sub>*n*</sub> (*i.e.*,  $x > 0$ ), the film can grow as shown in Fig. 1a. This is evidence that reveals that the decomposition of the methylthiolate *via* C–S bond cleavage is also catalyzed by Mo(CO)<sub>*n*</sub>, as done by Mo(CO)<sub>6</sub>.<sup>33</sup>

Generally, film growth by ALD shows a particular temperature window in which the growth-per-cycle (GPC) is weakly dependent on the growth temperature.<sup>18</sup> Fig. 2 shows the film thicknesses grown for 100 cycles ( $x = 3$  s and  $y = 1$  s) at different temperatures. Film growth is negligible at 60 °C. However, as the growth temperature becomes higher, the film thickness increases with the growth temperature and then saturates at 100 °C. The typical plateau of the GPC is observed in a temperature range of 100–120 °C. ALD process at higher temperatures than 120 °C results in a rapid increase of the GPC due to the uncontrolled thermal decomposition of precursors.

In addition, due to the self-limiting nature of ALD, the film thickness linearly increases with the number of ALD cycles. This is a great advantage of ALD because the thickness of the film can be controlled on an angstrom scale by the number of ALD cycles with a value of GPC. Fig. 3a shows thicknesses of MoS<sub>2</sub> films against the number of ALD cycles. The GPC of MoS<sub>2</sub> at 100 °C was evaluated to be  $0.11 \pm 0.01$  nm per cycle (when  $x = 4$  s and  $y = 1.5$  s) from the slope in the figure.

### 3.2 Characterization of MoS<sub>2</sub> thin film grown by ALD

Since the temperature window for our ALD chemistry is very low for the film to be crystallized, the films grown in this temperature range (100–120 °C) are shown to be amorphous by TEM and XRD analysis (see Fig. 5b and 6). If the ALD MoS<sub>2</sub>

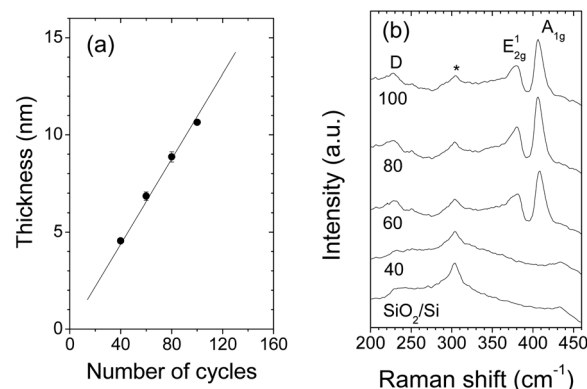


Fig. 3 (a) Thickness of MoS<sub>2</sub> films against number of ALD cycles. (b) Raman spectra (532 nm laser excitation) of MoS<sub>2</sub> films that were grown for various numbers of ALD cycles (the numbers on each spectrum). ALD was performed on SiO<sub>2</sub>/Si at 100 °C ( $x = 4$  s and  $y = 1.5$  s).

films were completely amorphous, no clear peaks should be visible in Raman spectra.<sup>38</sup> However the Raman spectra in Fig. 3b reveal that the amorphous MoS<sub>2</sub> film grown on SiO<sub>2</sub>/Si has a locally-ordered S–Mo–S unit with an atomic arrangement of 2H–MoS<sub>2</sub>. In the 2H structure of molybdenite (naturally occurring MoS<sub>2</sub>), an atomic plane of Mo is sandwiched between two atomic planes of S in a trigonal prismatic arrangement. For the bulk MoS<sub>2</sub>, the characteristic E<sub>2g</sub><sup>1</sup> (in-plane) and A<sub>1g</sub> (out-of-plane) Raman modes appear at 383 and 408 cm<sup>−1</sup>, respectively.<sup>39,40</sup>

The ALD MoS<sub>2</sub> films grown with more than 60 ALD cycles clearly show the characteristic E<sub>2g</sub><sup>1</sup> mode at 381 cm<sup>−1</sup> and the A<sub>1g</sub> mode at 406 cm<sup>−1</sup>. However the film grown for 40 cycles does not show any MoS<sub>2</sub> peak as compared with the Raman spectrum of the SiO<sub>2</sub>/Si substrate (the Si peak at 304 cm<sup>−1</sup> is marked with an asterisk in Fig. 3b). The E<sub>2g</sub><sup>1</sup> and A<sub>1g</sub> peaks also show a significant red-shift of 2 cm<sup>−1</sup> and broadening of the characteristic modes compared to the bulk MoS<sub>2</sub>. While the bulk or few-layered MoS<sub>2</sub> generally show a line width (full width at half maximum, FWHM) range of 2–6 cm<sup>−1</sup> for both peaks,<sup>40</sup> the FWHM of ALD MoS<sub>2</sub> films (12–14 cm<sup>−1</sup>) is much broader. It is possibly due to the locally-ordered microstructure. Recently, it has been reported that the E<sub>2g</sub><sup>1</sup> and A<sub>1g</sub> peaks can be shifted down and broadened for nanoparticles.<sup>11,41,42</sup>

Generally, the number of S–Mo–S layers in MoS<sub>2</sub> can be determined from the wavenumber difference ( $\Delta$ ) between E<sub>2g</sub><sup>1</sup> and A<sub>1g</sub> peaks, because the frequency of the former decreases and that of the latter increases with the number of layers.<sup>40</sup> For MoS<sub>2</sub> films with a higher number of layers than 5–6 layers, the  $\Delta$  values are around 25 cm<sup>−1</sup>. Even though the as-grown film by ALD does not show the layered crystalline structure in TEM and XRD analyses, since the thicknesses of the as-grown MoS<sub>2</sub> films with Raman peaks are thicker than 6 nm, the  $\Delta$  values of them are also around 25 cm<sup>−1</sup> as expected.

One more concern for the Raman spectra is the broad peak at 227 cm<sup>−1</sup> marked with D in Fig. 3b. Although there is no Raman active mode for crystalline MoS<sub>2</sub> in the wavenumber region,<sup>39</sup> the D peak appears only when the E<sub>2g</sub><sup>1</sup> and A<sub>1g</sub> peaks



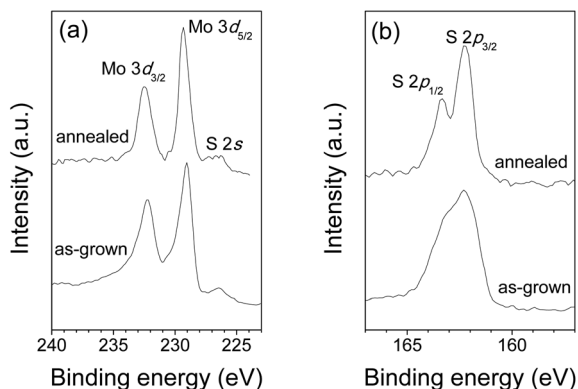


Fig. 4 XPS spectra of MoS<sub>2</sub> films as-grown by ALD or annealed at 900 °C for 5 min: Mo 3d (a) and S 2p (b) peaks. The binding energies were calibrated by using the C 1s peak (284.8 eV) of the adventitious carbon as an internal standard.

are observed. Raman inactive modes due to the Raman selection rule can be activated when the crystal symmetry is broken by defects.<sup>41,42</sup> We believe that the D peak may be attributed to the disorder in the microstructure of MoS<sub>2</sub> film. This behavior seems to be analogous to the disorder-induced mode found in graphitic carbon materials.<sup>43,44</sup> Similar results were also reported in deposited MoS<sub>2</sub> films by pulsed laser deposition.<sup>45</sup> They found that the intensity of the disorder peak (D) was relatively attenuated compared to the intensity of the A<sub>1g</sub> peak by annealing the samples because the crystallinity was improved.

The as-grown MoS<sub>2</sub> film was also characterized by X-ray photoelectron spectroscopy (XPS) as shown in Fig. 4. The spectra were obtained on the surface sputtered by 2 keV Ar<sup>+</sup> for 3 s in order to remove the adventitious carbon. The characteristic binding energies of Mo 3d<sub>3/2</sub> and 3d<sub>5/2</sub>, which are attributed to Mo<sup>4+</sup>, were observed at 232.3 and 229.1 eV, respectively.<sup>38,46</sup> For the binding energies of S 2p<sub>1/2</sub> and 2p<sub>3/2</sub> for divalent sulfide ion (S<sup>2-</sup>), the 2p<sub>3/2</sub> peak was observed at 162.3 eV, and the 2p<sub>1/2</sub> peak was not clearly resolved but appeared as a shoulder of the 2p<sub>3/2</sub> peak. These binding energy values are consistent with the previous reports for MoS<sub>2</sub>.<sup>38,46</sup> However the stoichiometric ratio of S/Mo is estimated to be 1.21 for the as-grown film, possibly due to partial oxidation of the surface. Indeed, high oxygen content is detected on the surface with an O/S ratio of 0.85 while the carbon content is negligible (~0.1 at%). Furthermore, the oxygen concentration in the as-grown film rapidly decreases during XPS depth profiling (see Fig. S1 in ESI<sup>†</sup>). This supports the partial oxidation of the surface due to vulnerable nature of the as-grown film in air.

In order to crystallize the amorphous MoS<sub>2</sub>, the as-grown film was annealed at 900 °C for 5 min under Ar atmosphere. The XPS spectra of the annealed film are also shown in Fig. 4. The Mo 3d<sub>3/2</sub> and 3d<sub>5/2</sub> peaks are located at 232.5 and 229.3 eV, respectively, and the S 2p doublet is clearly resolved at 163.3 and 162.2 eV after the annealing. In addition, the stoichiometric ratio of S/Mo is 2.01 and neither oxygen nor carbon atoms are detected on the annealed film.

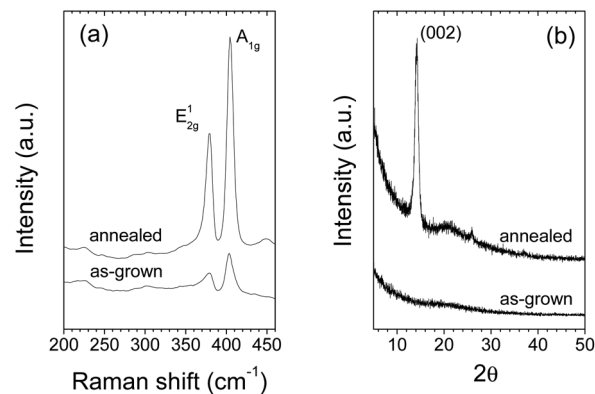


Fig. 5 Raman spectra (a) and XRD patterns (b) of MoS<sub>2</sub> films as-grown by ALD or annealed at 900 °C for 5 min.

After the annealing, the Raman modes become much stronger and narrower (FWHM ~9 cm<sup>-1</sup>), compared with the as-grown film (Fig. 5a). The D peak at 227 cm<sup>-1</sup>, originated from the disorder of MoS<sub>2</sub>, is also relatively attenuated compared with that of the as-grown film. But the  $\Delta$  value was not changed due to its 15 nm-thick thickness. For the same specimen, we investigated the crystal structure by XRD and high resolution TEM. The strong peak ( $2\theta = 14.27$ ) in Fig. 5b is attributed to (002) basal planes, for which interplanar spacing ( $d_{002}$ ) is calculated to be ~0.625 nm from the  $2\theta$  value. This indicates a little expansion (~1.7%) of the layer spacing in comparison to that (0.615 nm) of molybdenite.<sup>47</sup> The cross-sectional high resolution TEM image (Fig. 6) also shows that the S–Mo–S layers are aligned with the (002) basal plane parallel to the substrate. The averaged  $d_{002}$  obtained from the TEM

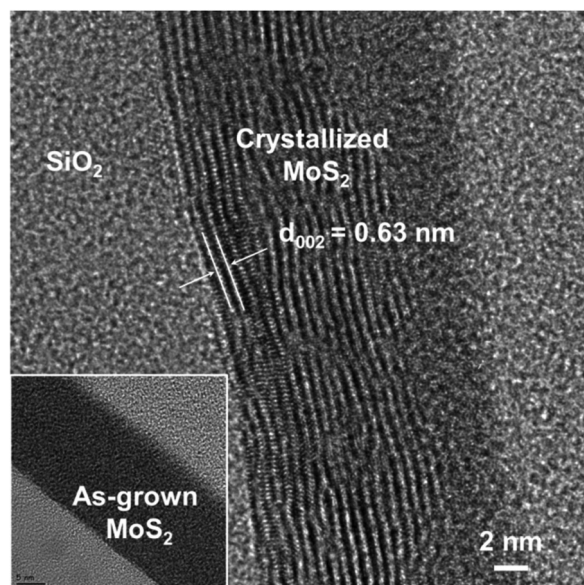


Fig. 6 Cross-sectional high resolution TEM image of the MoS<sub>2</sub> film annealed at 900 °C for 5 min. The TEM image in the inset shows the amorphous nature of the as-grown film.

image is around 0.63 nm, which is also consistent with the  $d_{002}$  value obtained by XRD. The crystallization of MoS<sub>2</sub> in the parallel direction of the substrate will be advantageous to prepare electronic devices based on MoS<sub>2</sub> such as transistors. However, since the film is not fully crystallized in its thickness due to the short annealing time (5 min), the crystallization process of the as-grown film should be optimized for the device fabrication.

## 4 Conclusions

In summary, we propose a novel chemical route for MoS<sub>2</sub> ALD using Mo(CO)<sub>6</sub> and DMDS as Mo and S precursors, respectively. Mo(CO)<sub>6</sub> is chemically adsorbed to be Mo(CO)<sub>*n*</sub> ( $n \leq 5$ ) in the first-half reaction, and the methylthiolate intermediate from the dissociative chemisorption of DMDS in the second-half reaction may undergo additional decomposition to produce sulfur adatoms, possibly owing to the catalytic effect of the chemisorbed Mo(CO)<sub>*n*</sub>. Even though the as-grown film is amorphous due to the low growth temperature (100 °C), it clearly shows the characteristic Raman modes ( $E_{2g}^1$  and  $A_{1g}$ ) of MoS<sub>2</sub>. The as-grown amorphous MoS<sub>2</sub> may be utilized for catalysis applications such as electrochemical HER. In addition, the crystallized MoS<sub>2</sub> by annealing may be used for the electronic applications, since the annealing process results in crystallization of the (002) basal planes in a parallel direction to the SiO<sub>2</sub>/Si substrate.

## Acknowledgements

This work was supported by Konkuk University in 2012. The authors thank H. K. Kang and M. K. Cho (Advanced Analysis Center, KIST) for XPS and TEM analyses, respectively.

## Notes and references

- 1 A. K. Geim, *Science*, 2009, **324**, 1530.
- 2 S. Z. Butler, *et al.*, *ACS Nano*, 2013, **7**, 2898.
- 3 M. Chhowalla, H. S. Shin, G. Eda, L. J. Li, K. P. Loh and H. Zhang, *Nat. Chem.*, 2013, **5**, 263.
- 4 Q. H. Wang, K. Kalantar-Zadeh, A. Kis, J. N. Coleman and M. S. Strano, *Nat. Nanotechnol.*, 2012, **7**, 699.
- 5 J. Yang and H. S. Shin, *J. Mater. Chem. A*, 2014, **2**, 5979.
- 6 K. F. Mak, C. Lees, J. Hone, J. Shan and T. F. Heinz, *Phys. Rev. Lett.*, 2010, **105**, 136805.
- 7 K. S. Novoselov, D. Jiang, F. Schedin, T. J. Booth, V. V. Khotkevich, S. V. Morozov and A. K. Geim, *Proc. Natl. Acad. Sci. U. S. A.*, 2005, **102**, 10451.
- 8 B. Radisavljevic, A. Radenovic, J. Brivio, V. Giacometti and A. Kis, *Nat. Nanotechnol.*, 2011, **6**, 147.
- 9 S. Das, H. Y. Chen, A. V. Penumatcha and J. Appenzeller, *Nano Lett.*, 2013, **13**, 100.
- 10 T. F. Jaramillo, K. P. Jorgensen, J. Bonde, J. H. Nielsen, S. Horch and I. Chorkendorff, *Science*, 2007, **317**, 100.
- 11 Y. Li, H. Wang, W. L. Xie, Y. Liang, G. Hong and H. Dai, *J. Am. Chem. Soc.*, 2011, **133**, 7296.
- 12 F. Schwierz, *Proc. IEEE*, 2013, **101**, 1567.
- 13 Y. H. Lee, X. Q. Zhang, W. Zhang, M. T. Chang, C. T. Lin, K. D. Chang, Y. C. Yu, J. T. W. Wang, C. S. Chang, L. J. Li and T. W. Lin, *Adv. Mater.*, 2012, **24**, 2320.
- 14 Y. Zhan, Z. Liu, S. Najmaei, P. M. Ajayan and J. Lou, *Small*, 2012, **8**, 966.
- 15 X. Wang, H. Feng, Y. Wu and L. Jiao, *J. Am. Chem. Soc.*, 2013, **135**, 5304.
- 16 Y. Yu, C. Li, Y. Liu, L. Su, Y. Zhang and L. Cao, *Sci. Rep.*, 2013, **3**, 1866.
- 17 B. Meyer, *Chem. Rev.*, 1976, **76**, 367.
- 18 S. M. George, *Chem. Rev.*, 2010, **110**, 111.
- 19 M. Diskus, O. Nilsen and H. Fjellvag, *J. Mater. Chem.*, 2011, **21**, 705.
- 20 D. Seghete, G. B. Rayner Jr., A. S. Cavanagh, V. R. Anderson and S. M. George, *Chem. Mater.*, 2011, **23**, 1668.
- 21 H. Wang, Z. Lu, S. Xu, D. Kong, J. J. Cha, G. Zheng, P. C. Hsu, K. Yan, D. Bradshaw, F. B. Prinz and Y. Cui, *Proc. Natl. Acad. Sci. U. S. A.*, 2013, **110**, 19701.
- 22 L. K. Tan, B. Liu, J. H. Teng, S. Guo, H. Y. Low and K. P. Loh, *Nanoscale*, 2014, **6**, 10584.
- 23 C. Yim, M. O'Brien, N. McEvoy, S. Winters, I. Mirza, J. G. Lunney and G. S. Duesberg, *Appl. Phys. Lett.*, 2014, **104**, 103114.
- 24 T. Ohta, F. Ciccoira, P. Doppelt, L. Beitone and P. Hoffmann, *Chem. Vap. Deposition*, 2001, **7**, 33.
- 25 R. Chellappa and D. Chandra, *J. Chem. Thermodyn.*, 2005, **37**, 377.
- 26 J. S. Cross and G. L. Schrader, *Thin Solid Films*, 1995, **259**, 5.
- 27 K. A. Gesheva and T. Ivanova, *Chem. Vap. Deposition*, 2006, **12**, 231.
- 28 K. Reddy and T. L. Brown, *J. Am. Chem. Soc.*, 1995, **117**, 2845.
- 29 H. H. Huang, C. S. Srekanth, C. S. Seet, X. Jiang and G. Q. Xu, *Surf. Sci.*, 1996, **365**, 769.
- 30 Z. Jiang, L. Xu and X. Huang, *J. Mol. Catal. A: Chem.*, 2009, **304**, 16.
- 31 P. Kruger, M. Petukhov, B. Domenichini, A. Berko and S. Bourgeois, *J. Phys. Chem. C*, 2012, **116**, 10617.
- 32 R. G. Nuzzo, B. R. Zegarski and L. H. Dubois, *J. Am. Chem. Soc.*, 1987, **109**, 733.
- 33 B. C. Wiegand and C. M. Friend, *Chem. Rev.*, 1992, **92**, 491.
- 34 B. Halevi and J. M. Vohs, *Surf. Sci.*, 2008, **602**, 198.
- 35 M. G. Roper and R. G. Jones, *Phys. Chem. Chem. Phys.*, 2008, **10**, 1336.
- 36 F. P. Cometto, V. A. Macagno, P. Parcedes-Olivera, E. M. Patrito, H. Ascolani and G. Zampieri, *J. Phys. Chem. C*, 2010, **114**, 10183.
- 37 D. M. VonNiederhausern, G. M. Wilson and N. F. Giles, *J. Chem. Eng. Data*, 2006, **51**, 1990.
- 38 N. T. McDevitt, J. E. Bultman and J. S. Zabinski, *Appl. Spectrosc.*, 1998, **52**, 1160.
- 39 J. L. Verble and T. J. Wieting, *Phys. Rev. Lett.*, 1970, **25**, 362.

- 40 C. Lee, H. Yan, L. E. Brus, T. F. Heinz, J. Hone and S. Ryu, *ACS Nano*, 2010, **4**, 2695.
- 41 G. L. Frey, R. Tenne, M. J. Matthews, M. S. Dresselhaus and G. Dresselhaus, *Phys. Rev. B: Condens. Matter*, 1999, **60**, 2883.
- 42 A. P. S. Gaur, S. Sahoo, M. Ahmadi, M. J. F. Guinel, S. K. Gupta, R. Pandey, S. K. Dey and R. S. Katiyar, *J. Phys. Chem. C*, 2013, **117**, 26262.
- 43 Y. S. Min, E. J. Bae, B. S. Oh, D. Kang and W. Park, *J. Am. Chem. Soc.*, 2005, **127**, 12498.
- 44 E. J. Bae, Y. S. Min, J. H. Ko, D. Kang and W. Park, *Chem. Mater.*, 2005, **17**, 5141.
- 45 N. T. McDevitt, J. S. Zabinski, M. S. Donley and J. E. Bultman, *Appl. Spectrosc.*, 1994, **48**, 733.
- 46 D. Merki, S. Fierro, H. Vrubel and X. Hu, *Chem. Sci.*, 2011, **2**, 1262.
- 47 B. Schonfeld, J. J. Huang and S. C. Moss, *Acta Crystallogr., Sect. B: Struct. Sci.*, 1983, **39**, 404.